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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/687,048	10/13/2000	Tae Heon Lee	AMKOR-052A	1120
7663	7590	06/16/2005		EXAMINER
STETINA BRUNDA GARRED & BRUCKER 75 ENTERPRISE, SUITE 250 ALISO VIEJO, CA 92656			NGUYEN, DILINH P	
			ART UNIT	PAPER NUMBER
			2814	

DATE MAILED: 06/16/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)
	09/687,048	LEE ET AL.
	Examiner	Art Unit
	DiLinh Nguyen	2814

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) Responsive to communication(s) filed on 05 May 2005.
- 2a) This action is FINAL. 2b) This action is non-final.
- 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) Claim(s) 16, 17, 19-26, 28-32, 34 and 35 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) Claim(s) _____ is/are allowed.
- 6) Claim(s) 16, 17, 19-26, 28-32, 34 and 35 is/are rejected.
- 7) Claim(s) _____ is/are objected to.
- 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) The specification is objected to by the Examiner.
- 10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 - a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|---|--|
| 1) <input type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____. |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date <u>3/21/05, 4/22/05</u> . | 6) <input type="checkbox"/> Other: _____. |

DETAILED ACTION

Response to Amendment

1. The amendment filed 5/5/05 is objected to under 35 U.S.C. 132(a) because it introduces new matter into the disclosure. 35 U.S.C. 132(a) states that no amendment shall introduce new matter into the disclosure of the invention. The added material which is not supported by the original disclosure is as follows: at least portions of the bottom surfaces of the outer leads of each set each being of a first length and at least a portion of the bottom surface of the inner lead of each set being of a second length and wherein the portions of the bottom surfaces of the inner and outer leads which are of the second length and the first length, respectively, are completely exposed in the encapsulation material.

Applicant is required to cancel the new matter in the reply to this Office Action.

Claim Rejections - 35 USC § 112

2. The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

3. Claims 16, 19-22, 24-25, 28-31 and 34-35 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

At least portions of the bottom surfaces of the outer leads of each set each being of a first length and at least a portion of the bottom surface of the inner lead of each set being of a second length and wherein the portions of the bottom surfaces of the inner and outer leads which are of the second length and the first length, respectively, are completely exposed in the encapsulation material (claims 16, 25 and 30-31); the exposed portion of the bottom surface of each of the outer leads exceeds the second length of the exposed portion of the bottom surface of the inner lead (claims 19, 28 and 34); the exposed portion of the bottom surface of each of the outer leads is less than the second length of the exposed portion of the bottom surface of the inner lead (claims 20, 29 and 35); the exposed portion of the bottom surface of the chip paddle (claims 21-22); at least a portion of the bottom surface of the at least one tie bar is exposed in the encapsulation material (claim 24) are new subject matters.

Claim Rejections - 35 USC § 102

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

5. Claims 16-17, 20, 23-26, 29-32, and 35 are rejected under 35 U.S.C. 102(e) as being anticipated by Okumura et al. (U.S. Pat. 5942794).

- Regarding claims 16, 25 and 31, Okumura et al. disclose a semiconductor package (fig. 5a-5b) comprising:

a chip paddle 20 defining opposed top and bottom surfaces and a plurality of sides and corners; and

at least two sets of leads extending along respective ones of the sides of the chip paddle in spaced relation thereto, each set of leads including at least two outer leads and at least one inner lead disposed between the outer leads, the inner and outer leads of each set each defining opposed top and bottom surfaces, with the bottom surfaces of the outer leads of each set each being of a first length and the bottom surface of the inner lead of each set being of a second length which is unequal to the first length;

a semiconductor chip 19 mounted to the top surface of the chip paddle and electrically connected to at least one of the inner and outer leads; and

an encapsulation material 15 covering the leadframe and the semiconductor chip 19 such that the bottom surfaces 16 of the inner and outer leads are exposed in the encapsulation material (fig. 5a).

- Regarding claims 17, 26 and 32, Okumura et al. disclose multiple sets of leads which extend along respective ones of each of the sides of the chip paddle 20 in spaced relation thereto (fig. 5b).
- Regarding claims 20, 29 and 35, Okumura et al. disclose that the first length of the bottom surface of each of the outer leads is less than the second length of the bottom surface of the inner lead (fig. 5b).
- Regarding claim 23, Okumura et al. disclose that one tie bar 9 attached to and extending from at least one of the corners of the chip paddle, the tie bar defining opposed top and bottom surfaces (fig. 5b).

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- Regarding claim 24, Okumura et al. disclose that the bottom surface of the at least one tie bar 9 is exposed in the encapsulation material 15 (fig. 5a).
- Regarding claim 30, Okumura et al. disclose that the encapsulation material 15 defines a generally planar bottom surface 15a; and the bottom surfaces 16 of the inner and outer leads are each generally planar and substantially flush with the bottom surface of the encapsulation material (fig. 5a).

Claim Rejections - 35 USC § 103

6. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

7. Claims 21-22, 19, 28 and 34 are rejected under 35 U.S.C. 103(a) as being unpatentable over Okumura et al. by (U.S. Pat. 5942794) in view of Applicant Admitted Prior Art (AAPA, figs. 1 and 3).

- Regarding claims 21, Okumura et al. substantially disclose all the limitations as claimed above except for the bottom surface of the chip paddle is exposed in the encapsulation material.

AAPA (figs. 1 and 3) discloses that the semiconductor package comprising the bottom surface 110 of the chip paddle is exposed in the encapsulation material 10 (fig. 2).

Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the device structure of Okumura et al. by having the bottom surface of the chip paddle is exposed, as taught by AAPA, in order to

provide a high reliability and reduce complexity of implementation for the semiconductor package (figs. 2 and 3).

- Regarding claim 22, AAPA (fig. 2) discloses the encapsulation material 10 defines a generally planar bottom surface; the bottom surface of the chip paddle is generally planar and substantially flush with the bottom surface of the encapsulation material; and the bottom surfaces of the inner and outer leads are each generally planar and substantially flush with the bottom surface of the encapsulation material (fig. 2).
- Regarding claims 19, 28 and 34, Okumura et al. disclose the plurality sets of leads extending along ones of the sides of the chip paddle (fig. 5b) and it would have been obvious to form the length of the outer leads exceeds the length of the inner lead (see the references: Corisis [U.S. Pat. 6271580], fig. 3 and Ando [JP 406163786] fig. 1b).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to DiLinh Nguyen whose telephone number is (571) 272-1712. The examiner can normally be reached on 8:00AM - 6:00PM (M-F).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

DLN



HOAI PHAM
PRIMARY EXAMINER